

To: **Techonology Unit: 2800**  
**Facsimile Number: 703-872-9306**

Total Pages Sent 8

From: **W. Daniel Swayze, Jr.**  
**Texas Instruments Incorporated**  
**Facsimile: 972-917-4418**  
**Phone: 972-917-5633**

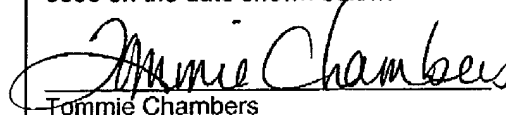
**RECEIVED**  
**CENTRAL FAX CENTER**

**OCT 04 2004**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**CERTIFICATION OF FACSIMILE TRANSMISSION**

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:

  
Tommie Chambers  
October 1, 2004  
Date

**FACSIMILE COVER SHEET**

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT (7 Pages)
<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT (# Month)
<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT (# Pages)	<input type="checkbox"/> APPEAL (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE (# Pages)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> CHANGE IN CORRESPONDENCE
<input type="checkbox"/> CONTINUATION APP'N (# Pages)	<input type="checkbox"/> ADDRESS
<input type="checkbox"/> DIVISIONAL APP'N	
<b>NAME OF INVENTOR(S):</b> Yoshino	
<b>RECEIPT DATE &amp; SERIAL NO.:</b> Serial No.: 09/909,013 Filing Date: 7/19/2001	
<b>TITLE OF INVENTION:</b> SEMICONDUCTOR PACKAGE INSULATION FILM AND MANUFACTURING METHOD THEREOF	
<b>TI FILE NO.:</b> TI-29448	<b>DEPOSIT ACCT. NO.:</b> 20-0668
<b>FAXED:</b> 10/01/2004 <b>DUE:</b> 09/26/2004 <b>ATTY/SEC'Y:</b> WDS/tbc	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated  
PO Box 655474, M/S 3999  
Dallas, TX 75265

Received on  
10-4-04 by  
C.F.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECEIVED  
CENTRAL FAX CENTER

OCT 04 2004

Applicant: Yoshino

Docket No: TI-29448

Serial No: 09/909,013

Examiner: Geyer, Scott

Filed: 7/19/2001

Art Unit: 2829

For: SEMICONDUCTOR PACKAGE INSULATION FILM AND  
MANUFACTURING METHOD THEREOF

AMENDMENT UNDER 37 C.F.R. § 1.116

Assistant Commissioner For Patents  
Washington, DC 20231

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being  
transmitted by facsimile to the U.S. Patent and Trademark  
Office at 703-872-9306 on 10-1-04:

*Tommie Chambers*  
Tommie Chambers

Dear Sir:

Responsive to the Office Action mailed July 26, 2004 in connection with the  
above identified application, Applicants respectfully submit the following amendments  
and remarks.